
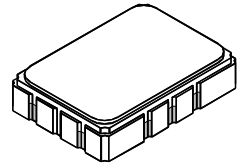




SF2037B-3

**76.500 MHz
SAW Filter**

- **Designed for SDARS IF Receiver**
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Differential or Single Ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)** 



SMP-03-S

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Max Soldering Profile	265°C for 10 s	


Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c	1	76.500			MHz
Passband	IL	1		10.0	12.0	dB
1dB Passband	BW_1		3.8	4.1		MHz
15dB Bandwidth	BW_{15}			6.7	6.8	MHz
30dB Bandwidth	BW_{30}			7.7	7.8	MHz
Amplitude Ripple over $f_c \pm 1.9$ MHz					0.5	1.10
Group Delay Variation over $f_c \pm 1.9$ MHz	GDV			65	150	ns _{p-p}
Rejection		1, 3	40	45		dB
50 to 65.44 MHz			39	43		
65.44 to 70.44 MHz			36	43		
70.44 to 72.04 MHz			38	49		
81.26 to 82.56 MHz			39	48		
82.56 to 86.50 MHz			41	48		
86.5 to 91.50 MHz			45	58		
91.50 to 100.000 MHz						
Operating Temperature Range	T_A	1	-40		+85	°C
Frequency Temperature Coefficient	FTC			-18		ppm/°C
Differential Input			175 ohms			
Differential Output			1000 ohms			
Case Style		6	SMP-03-S 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF2037B-3 YYWWS			

Electrical Connections

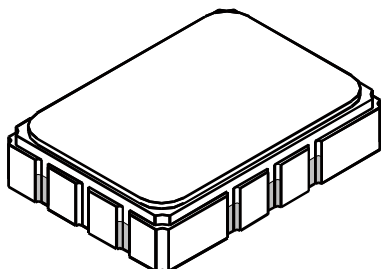
Connection	Port 1 Hot	Port 1 Ground Return or Hot	Port 2 Hot	Port 2 Ground Return or Hot	Case Ground
Terminals	10	1	5	6	All Others

Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.
10. ©Copyright 1999, RF Monolithics Inc.
11. Electrostatic Sensitive Device. Observe precautions for handling. 

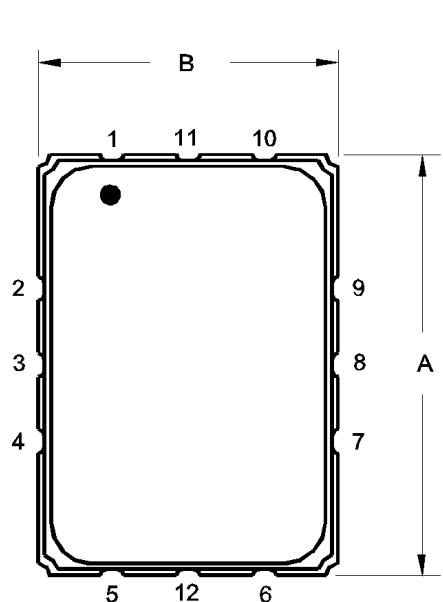
SMP-03-S Case 

12-Terminal Ceramic Surface-Mount Case
5 x 7 mm Nominal Footprint

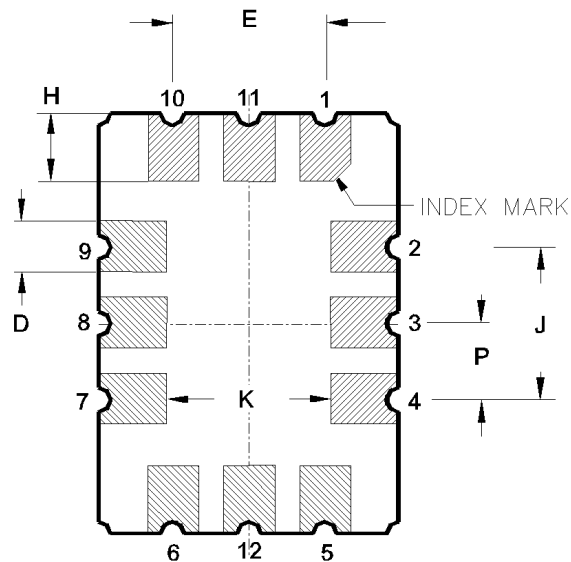
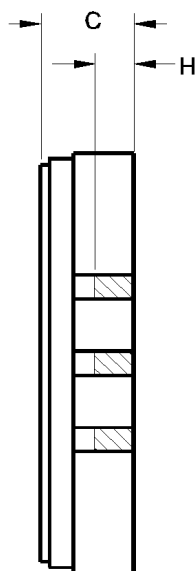


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.80				
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.1	1.13	0.034	0.039	0.044
J		2.54				
K		2.8				
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μinches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

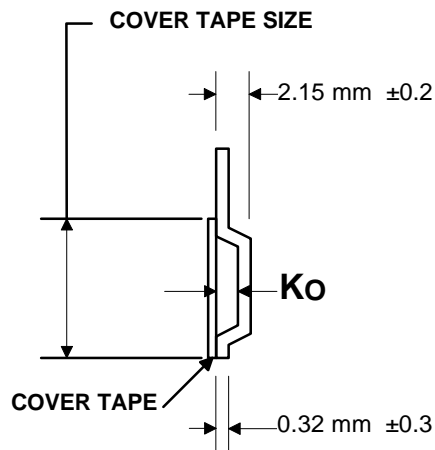
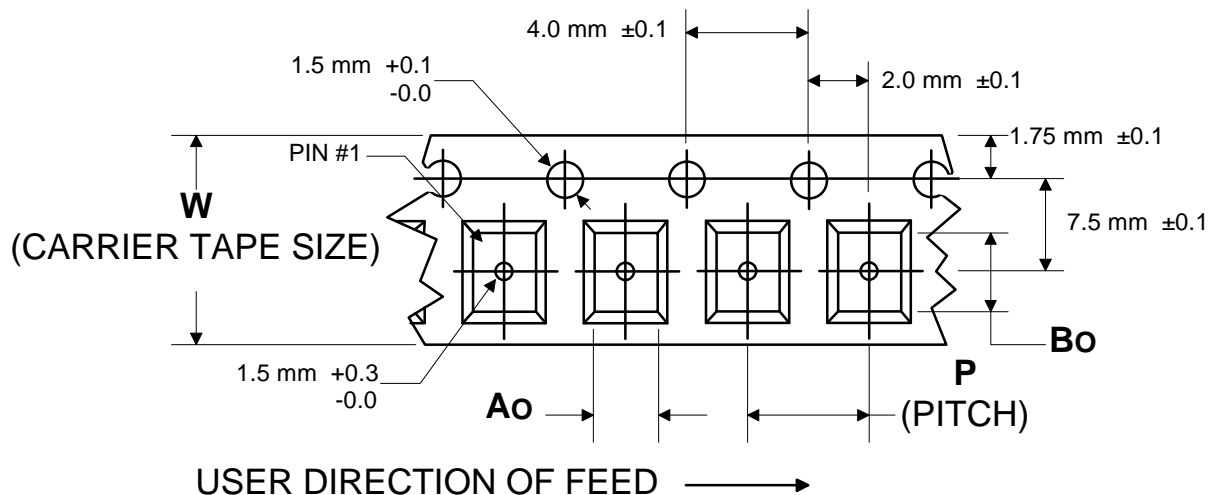


TOP VIEW



BOTTOM VIEW

COMPONENT ORIENTATION and DIMENSIONS



Carrier Tape Dimensions		
Ao	5.5 mm	±0.1
Bo	7.5 mm	±0.1
Ko	2.0 mm	±0.1
Pitch	8.0 mm	±0.1
W	16.0 mm	±0.3